Innovative Sensor Technology

physical. chemical. biological.

BondSens

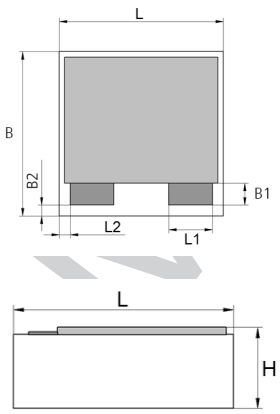
Platinum sensor

One of the worlds smallest platinum RTD

Benefits & Characteristics

- Very small size
- Full platinum RTD stability according to IEC 60751
- Very low drift
- Designed for Au-wire bonding
- Perfect for high volume applications with high integration rate
- Optimal for wearables, temperature control of LEDs or high power ICs
- Integratable with semiconductor devices
- Customer-specific sensor available upon request

Illustration[1)]



1) For actual size, see dimensions

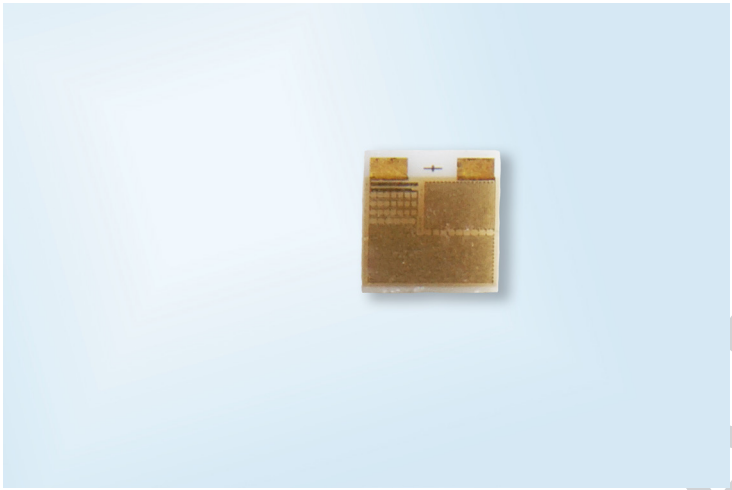
Technical Data

Operating temperature range:	-50 °C to +150 °C	
Nominal resistance:*	1000 Ω at 0 °C	
Characteristics curve:*	3850 ppm/K	
Long-term stability:	< 0.04 % at 1000 h at 130 °C	
Tolerance class (dependent on temperature range):*		IST AG reference
	IEC 60751 F0.3	B
Connection:*	3FC Au-Pads (bonding pads)	
Recommended applied current:[2)]	0.3 mA	
Special:	For dry environments only	

2) Self-heating must be considered

* Customer-specific alternatives available

Product Photo



Order Information - 3FC (Au-Pads - bonding pads)

Size	Dimensions (L / L1 /L2 x W / W1 / W2x H in mm)	F0.3 (class B)
Nominal resistance: 1000 Ω at 0 °C		
0707	0.75 / 0.2 / 0.05 x 0.75 / 0.1 / 0.05 x 0.3 (±0.1)	P1K0.0707.3FC.B.T
Order code		104316
Former order code		*310.01424*

Additional Documents

	Document name:
Application Note:	ATP_E

Innovative Sensor Technology IST AG, Stegrütistrasse 14, 9642 Ebnat-Kappel, Switzerland
Phone: +41 71 992 01 00 | Fax: +41 71 992 01 99 | Email: info@ist-ag.com | www.ist-ag.com